Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

1SS383T1G

Preferred Device

Dual Schottky Diode

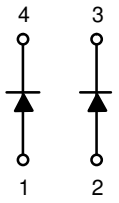
Dual 40 V, 300 mA Low V_F Schottky Diodes in 4−lead SC−82 package.

Features

- Low Forward Voltage: V_F = 0.48 V (typ) @ I_F = 100 mA
- Low Reverse Current: I_R = 5 μA (max)
- This is a Pb−Free Device*

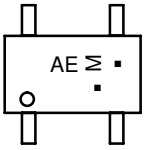
ON Semiconductor®

http://onsemi.com



SC−82
CASE 900AA

MARKING DIAGRAM



AE = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Continuous Reverse Voltage	V_R	40	V
Maximum Peak Forward Current*	I_{FM}	300	mA
Peak Forward Surge Current Pulse Width = 10 μs	$I_{FM(surge)}$	500	mA

THERMAL CHARACTERISTICS

Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation T_A = 25°C Derate above 25°C	P_D	200 (Note 1) 1.6 (Note 1)	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	625 (Note 1)	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
*Both Devices Active
1. FR−4 @ Minimum Pad.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Forward Voltage (I_F = 1.0 mA) (I_F = 10 mA) (I_F = 100 mA)	V_F	 − − −	 280 360 540	 − − 600	mV
Reverse Current (V_R = 40 V)	I_R	−	−	5	μA
Capacitance (V_R = 0, f = 1.0 MHz)	C_D	−	−	25	pF

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ORDERING INFORMATION

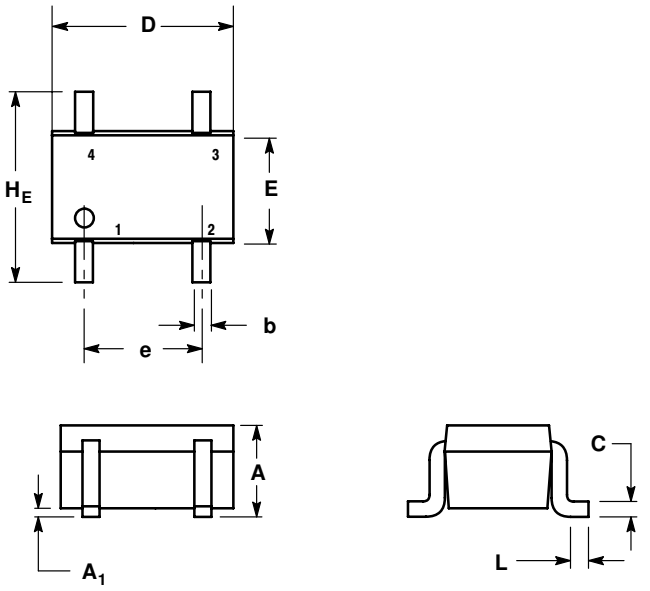
Device	Package	Shipping†
1SS383T1G	SC−82 (Pb−Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

PACKAGE DIMENSIONS

SC−82, 4 LEAD, GULL WING
CASE 900AA−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUMTHICKNESS OF BASE MATERIAL.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.80	0.90	1.00	0.032	0.035	0.04
A_1	0	−−−	0.10	0	−−−	0.004
b	0.10	0.20	0.30	0.004	0.008	0.012
C	0.10	0.18	0.25	0.004	0.007	0.010
D	1.80	2.00	2.20	0.071	0.079	0.087
E	1.15	1.25	1.35	0.045	0.049	0.053
e	1.30 BSC			0.051 BSC		
H_E	2.00	2.10	2.20	0.079	0.083	0.087
L	0.10	0.20	0.30	0.004	0.008	0.012

STYLE 1:
PIN 1. ANODE 1
2. ANODE 2
3. CATHODE 2
4. CATHODE 1

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
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